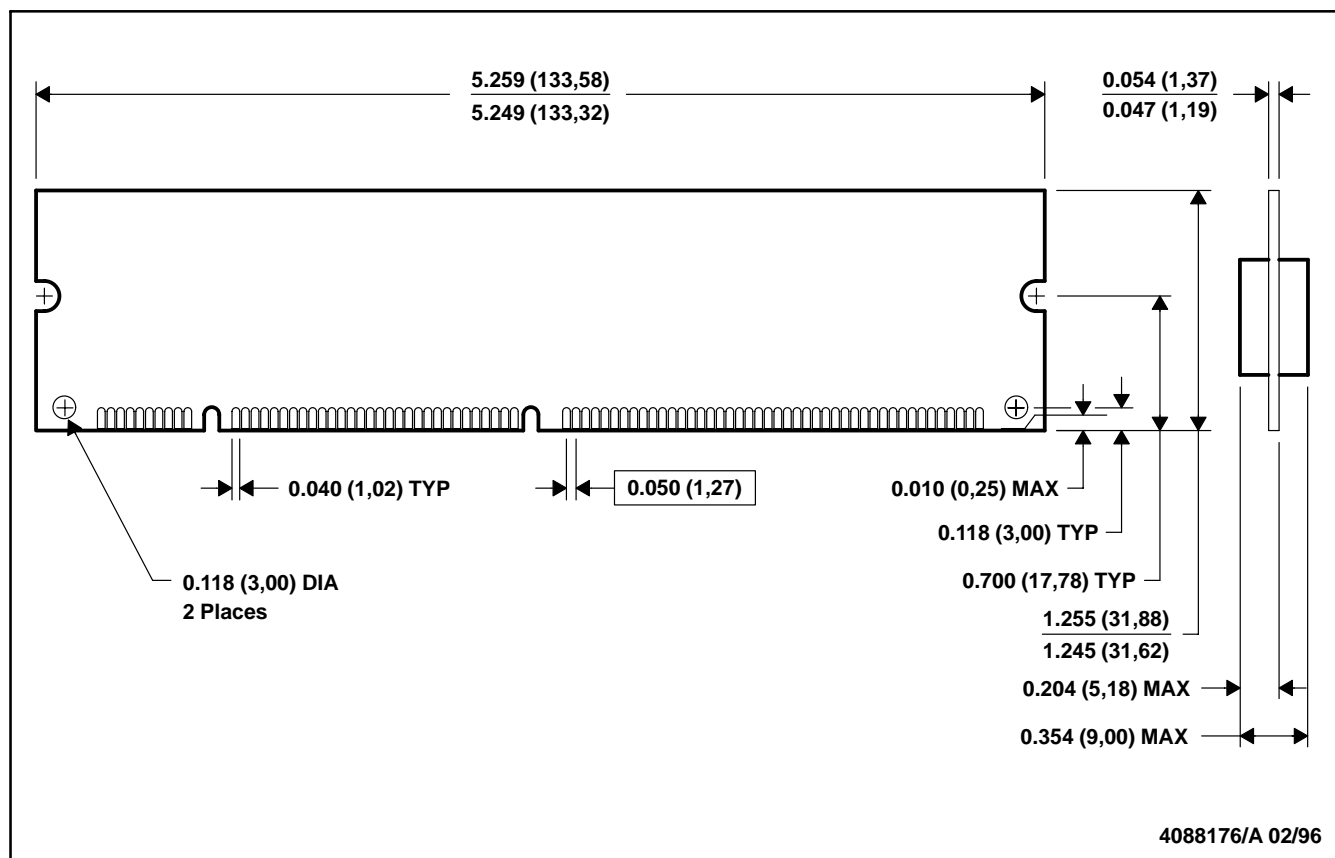


BN (R-PDIM-N168)

DUAL IN-LINE MEMORY MODULE



- NOTES: A. All linear dimensions are in inches (millimeters).  
B. This drawing is subject to change without notice.

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